

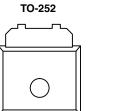
# N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
60	0.073 at V <sub>GS</sub> = 10 V	18.2	19.8		
	0.085 at V <sub>GS</sub> = 4.5 V	13.2	19.0		

#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Material categorization:
  For definitions of compliance please see



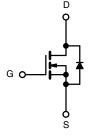


D

Drain Connected to Tab

#### **APPLICATIONS**

- DC/DC Converters
- DC/AC Inverters
- Motor Drives



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	60	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20				
Continuous Drain Current	T <sub>C</sub> = 25 °C	,	16.9			
Continuous Drain Current	T <sub>C</sub> = 70 °C	I <sub>D</sub>	13.6	A		
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	25	☐ ^			
Avalanche Current	I <sub>AS</sub>	15				
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	11.25	mJ		
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	В	41.7 <sup>b</sup>	W		
waximum rower bissipation	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	2.1			
Operating Junction and Storage Tempe	rature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Limit	Unit			
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	60	°C/W			
Junction-to-Case (Drain)	R <sub>thJC</sub>	3				

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Base on  $T_C$  = 25 °C.

E-mail: China@VBsemi TEL:86-755-83251052



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.0		3.0	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.6 A		0.073			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 6 A		0.083		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6.6 A		25		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			860		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, f = 1 MHz		85			
Reverse Transfer Capacitance	C <sub>rss</sub>			40			
Total Gate Charge <sup>c</sup>	Qq			19.8	30	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 6.6 \text{ A}$		3.6			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			4.1			
Gate Resistance	R <sub>a</sub>	f = 1 MHz	0.4	2	4	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_{I} = 9.6 \Omega$		11	20		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 5.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		18	27		
Fall Time <sup>c</sup>	t <sub>f</sub>	-		5	10		
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			38	57	ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_{i} = 9.6 \Omega$		58	87	1	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 5.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		18	27		
Fall Time <sup>c</sup>	t <sub>f</sub>	_		8	16		
Drain-Source Body Diode Ratings a	nd Characteri	stics <sup>b</sup> T <sub>C</sub> = 25 °C					
Continuous Current	Is				16.9		
Pulsed Current	I <sub>SM</sub>			1	25	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 5.2 A, V <sub>GS</sub> = 0 V		0.8	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 5.2 A, dl/dt = 100 A/μs		3	5	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	, , , , , , , , , , , , , , , , , , ,		50	75	nC	

### Notes:

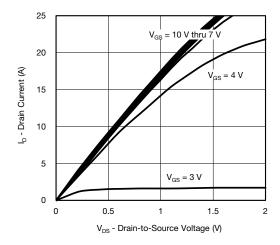
- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

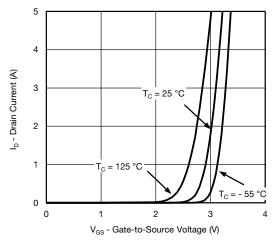
E-mail: China@VBsemi TEL:86-755-83251052



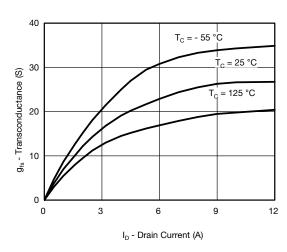
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



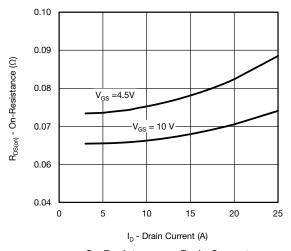
#### **Output Characteristics**



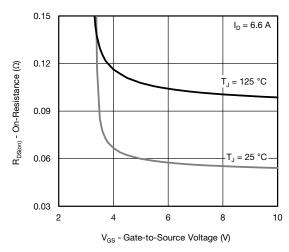
#### **Transfer Characteristics**



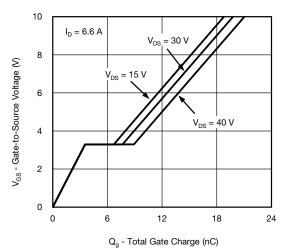
Transconductance



On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

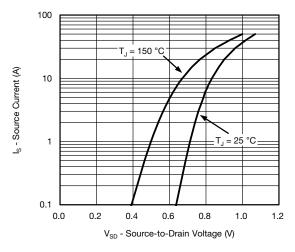


Gate Charge

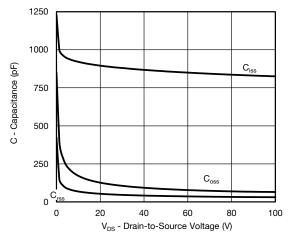
E-mail: China@VBsemi TEL:86-755-83251052



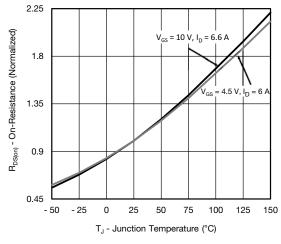
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



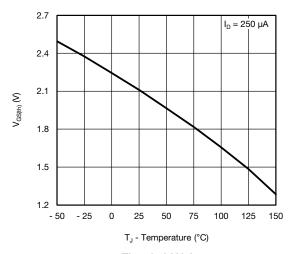
#### Source-Drain Diode Forward Voltage



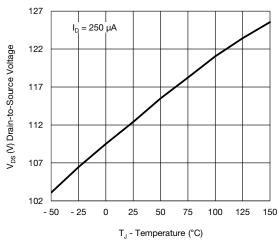
Capacitance



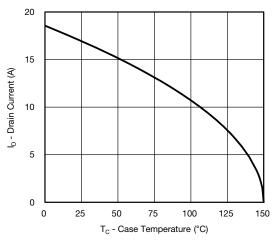
On-Resistance vs. Junction Temperature



**Threshold Voltage** 



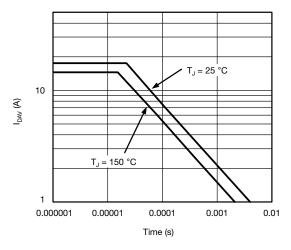
**Drain Source Breakdown vs. Junction Temperature** 

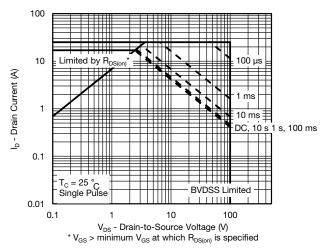


**Current Derating** 



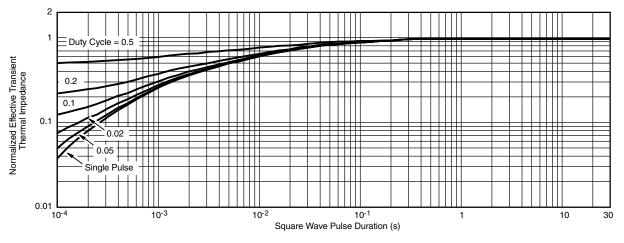
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time

Safe Operating Area

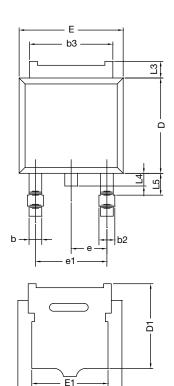


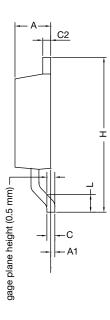
Normalized Thermal Transient Impedance, Junction-to-Case

E-mail: China@VBsemi TEL:86-755-83251052



## **TO-252AA Case Outline**





	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
Α	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
Е	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
Н	9.40	10.41	0.370	0.410
е	2.28 BSC		0.090 BSC	
e1	4.56	4.56 BSC		BSC
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T16-0236-Rev. P, 16-May-16				

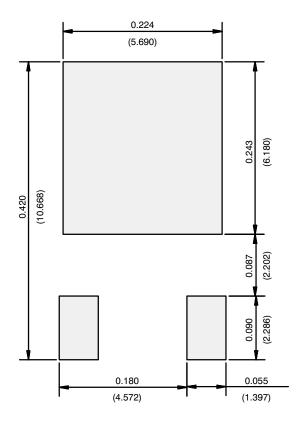
# DWG: 5347

• Dimension L3 is for reference only.

E-mail: China@VBsemi TEL:86-755-83251052



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

E-mail: China@VBsemi TEL:86-755-83251052



# **Disclaimer**

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.tw)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

## **Material Category Policy**

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be RoHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.tw)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below:

614233C 648584F NTNS3A92PZT5G IRFD120 IRFF430 JANTX2N5237 2N7000 2SK2464-TL-E FCA20N60\_F109 FDZ595PZ AOD464 2SK2267(Q) 2SK2545(Q,T) 405094E 423220D MIC4420CM-TR VN1206L 614234A 715780A SSM6J414TU,LF(T 751625C IPP60R600P6XKSA1 RJK60S5DPK-M0#T0 PSMN4R2-30MLD TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 NTE2969 NTE6400A DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6 C3M0021120D DMN13M9UCA6-7 BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IRF40SC240ARMA1